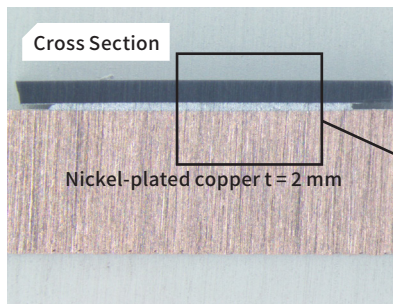
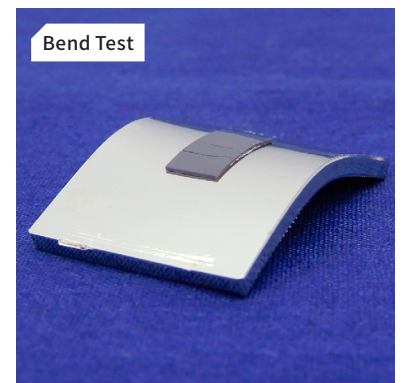
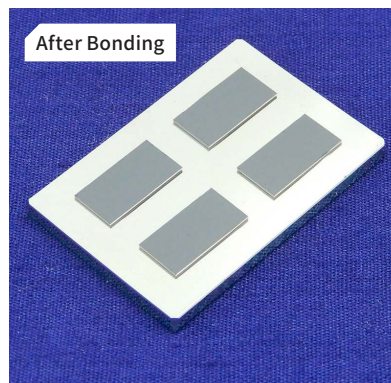
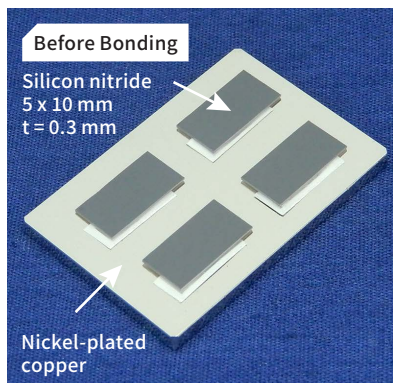




Application

Bonding

Ceramic Plate and Heatsink Simultaneous Bonding



Key Points

- ✓ Silicon nitride and nickel-plated copper bonding
- ✓ 4 Ceramic plates bonded simultaneously
- ✓ Heat shock tested (-50°C to 500°C)
- ✓ Powered by electricity and air
- ✓ Bonding at room-temperature and under atmospheric conditions

System Used

- ✓ 15MZs



AP-E-0096A4-2026082601